

DERWENT-ACC-NO: 2003-827487

DERWENT-WEEK: 200377

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TITLE: Automated chuck cleaning apparatus

INVENTOR: KIM, C S; LEE, J H

PATENT-ASSIGNEE: SAMSUNG ELECTRONICS CO LTD[SMSU]

PRIORITY-DATA: 2001KR-0087109 (December 28, 2001)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
KR <u>2003056808</u>	A July 4, 2003	N/A	001	H01L 021/66

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
KR2003056808A	N/A	2001KR-0087109	December 28, 2001

INT-CL (IPC): H01L021/66

ABSTRACTED-PUB-NO: KR2003056808A

BASIC-ABSTRACT:

NOVELTY - An automated chuck cleaning apparatus is provided to be capable of easily removing particles existing on a chuck by using a chuck cleaning assembly having a vacuum cleaner and a rotary brush instead of a manual removing process.

DETAILED DESCRIPTION - An automated chuck cleaning apparatus is provided with a chuck(15) installed for loading a wafer and a chuck cleaning assembly(17). The chuck cleaning assembly includes a vacuum cleaner capable of absorbing particles existing on the chuck and a rotary brush(25) capable of physically removing the particles. Preferably, the chuck cleaning assembly is connected with a head plate of a probing apparatus. Preferably, the chuck cleaning assembly is formed into a corn shape having the lower portion larger than the upper portion.

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: AUTOMATIC CHUCK CLEAN APPARATUS

DERWENT-CLASS: U11

EPI-CODES: U11-F01B1;

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